

Single N-channel MOSFET

ELM17412GA-S

■ General description

ELM17412GA-S uses advanced trench technology to provide excellent $R_{ds(on)}$, low gate charge and operation with gate voltages as low as 2.5V.

■ Features

- $V_{ds}=30V$
- $I_d=2.1A$ ($V_{gs}=10V$)
- $R_{ds(on)} < 90m\Omega$ ($V_{gs}=10V$)
- $R_{ds(on)} < 100m\Omega$ ($V_{gs}=4.5V$)
- $R_{ds(on)} < 160m\Omega$ ($V_{gs}=2.5V$)

■ Maximum absolute ratings

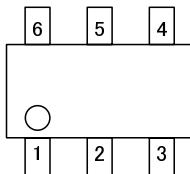
Parameter	Symbol	Limit	Unit	Note
Drain-source voltage	V_{ds}	30	V	
Gate-source voltage	V_{gs}	± 12	V	
Continuous drain current	I_d	2.1	A	1
Ta=70°C		1.7		
Pulsed drain current	I_{dm}	10	A	2
Power dissipation	P_d	0.625	W	1
Ta=70°C		0.400		
Junction and storage temperature range	T_j, T_{stg}	-55 to 150	°C	

■ Thermal characteristics

Parameter		Symbol	Typ.	Max.	Unit	Note
Maximum junction-to-ambient	t≤10s	$R_{\theta ja}$	175	200	°C/W	1
Maximum junction-to-ambient	Steady-state		200	250	°C/W	
Maximum junction-to-lead	Steady-state	$R_{\theta jl}$	130	160	°C/W	3

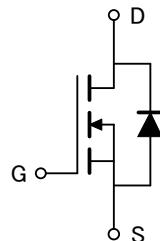
■ Pin configuration

SC-70-6 (TOP VIEW)



Pin No.	Pin name
1	DRAIN
2	DRAIN
3	GATE
4	SOURCE
5	DRAIN
6	DRAIN

■ Circuit



Single N-channel MOSFET

ELM17412GA-S

■ Electrical characteristics

$T_a=25^\circ C$

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	
STATIC PARAMETERS							
Drain-source breakdown voltage	BVdss	$I_d=250\mu A, V_{gs}=0V$	30			V	
Zero gate voltage drain current	Idss	Vds=16V			1	μA	
		Vgs=0V	Tj=55°C		5		
Gate-body leakage current	Igss	Vds=0V, Vgs=±12V			100	nA	
Gate threshold voltage	Vgs(th)	Vds=Vgs, Id=250 μA	1.0	1.5	1.8	V	
On state drain current	Id(on)	Vgs=4.5V, Vds=5V	10			A	
Static drain-source on-resistance	Rds(on)	Vgs=10V			69	$m\Omega$	
		Id=2.1A	Tj=125°C		108		
		Vgs=4.5V, Id=1.3A			78	100	$m\Omega$
		Vgs=2.5V, Id=1A			130	160	$m\Omega$
Forward transconductance	Gfs	Vds=5V, Id=2.1A			8.5		S
Diode forward voltage	Vsd	Is=1A, Vgs=0V			0.8	1.0	V
Max. body-diode continuous current	Is				2.5	A	
DYNAMIC PARAMETERS							
Input capacitance	Ciss	Vgs=0V, Vds=15V, f=1MHz			226	270	pF
Output capacitance	Coss				39		pF
Reverse transfer capacitance	Crss				29		pF
Gate resistance	Rg	Vgs=0V, Vds=0V, f=1MHz			1.4	1.7	Ω
SWITCHING PARAMETERS							
Total gate charge	Qg	Vgs=4.5V, Vds=15V, Id=2.1A			3.0	3.6	nC
Gate-source charge	Qgs				0.4		nC
Gate-drain charge	Qgd				1.2		nC
Turn-on delay time	td(on)	Vgs=5V, Vds=15V RL=7.1 Ω , Rgen=6 Ω			2.8	4.0	ns
Turn-on rise time	tr				2.1	3.0	ns
Turn-off delay time	td(off)				17.4	21.0	ns
Turn-off fall time	tf				2.1	3.0	ns
Body diode reverse recovery time	trr	If=2.1A, dl/dt=100A/ μs			9.1	11.0	ns
Body diode reverse recovery charge	Qrr	If=2.1A, dl/dt=100A/ μs			3.4	4.0	nC

NOTE :

1. The value of $R\theta_{ja}$ is measured with the device mounted on 1in² FR-4 board of 2oz. Copper, in still air environment with $T_a=25^\circ C$. The value in any given applications depends on the user's specific board design, The current rating is based on the $t \leq 10s$ thermal resistance rating.
2. Repetitive rating, pulse width limited by junction temperature.
3. The $R\theta_{ja}$ is the sum of the thermal impedance from junction to lead $R\theta_{jl}$ and lead to ambient.
4. The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5%max.
5. These tests are performed with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_a=25^\circ C$. The SOA curve provides a single pulse rating.

Single N-channel MOSFET

ELM17412GA-S

■ Typical electrical and thermal characteristics

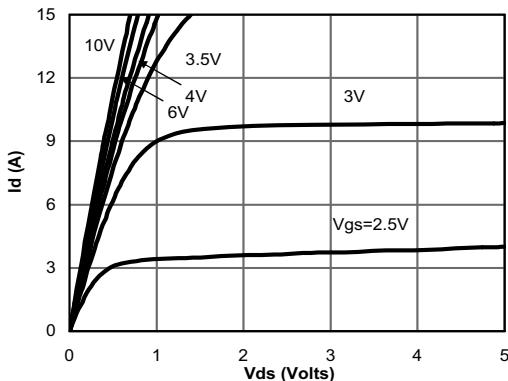


Fig 1: On-Region Characteristics

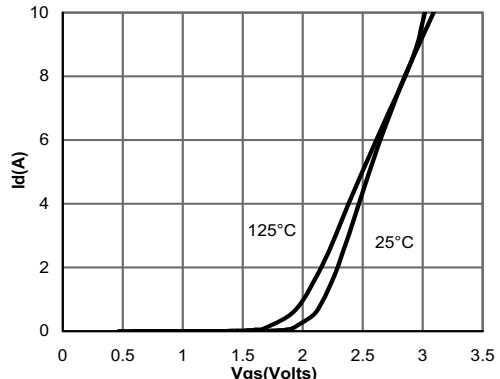


Figure 2: Transfer Characteristics

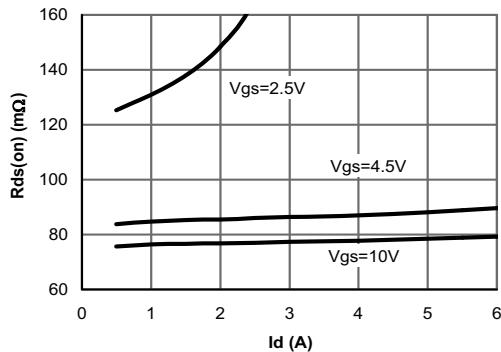


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

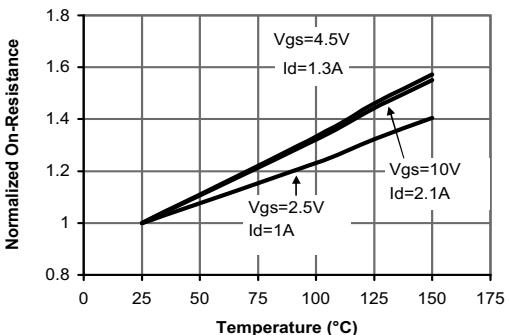


Figure 4: On-Resistance vs. Junction Temperature

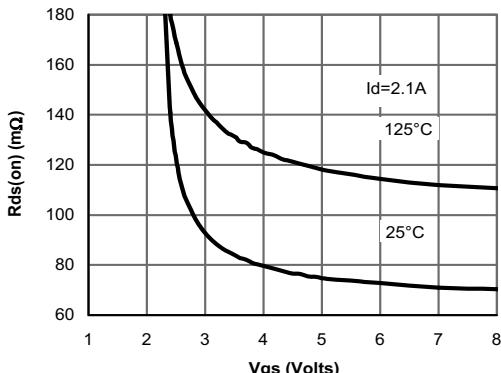


Figure 5: On-Resistance vs. Gate-Source Voltage

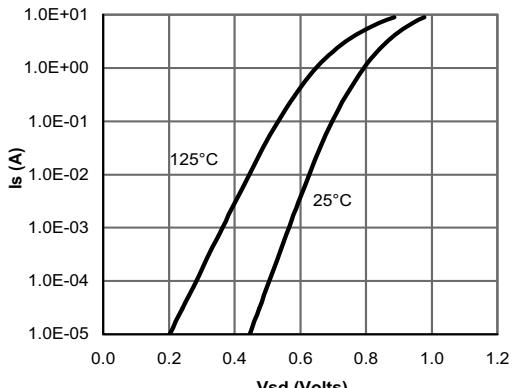


Figure 6: Body-Diode Characteristics

Single N-channel MOSFET

ELM17412GA-S

